



<b>Title of Change:</b>	PCN Update Notice – Cancellation of FPCN FPCN21043X which announced the transfer of the VHC1G, VHC1GT and SZ product family devices in the SC88A package to the TS18 wafer process at Tower Semiconductor and a change to the BOM for these same products to include Pd coated wire and Henkel mold compound.
<b>Proposed first ship date:</b>	26 July 2016
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or <Shero.Gao@onsemi.com>
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or <Jose.Aguilar@onsemi.com>.
<b>Type of notification:</b>	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
<b>Change category:</b>	<input checked="" type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change   X Other _____

<b>Change Sub-Category(s):</b>		<input type="checkbox"/> Datasheet/Product Doc change
<input type="checkbox"/> Manufacturing Site Change/Addition	<input checked="" type="checkbox"/> Material Change	<input type="checkbox"/> Shipping/Packaging/Marking
<input checked="" type="checkbox"/> Manufacturing Process Change	<input type="checkbox"/> Product specific change	Other: _____
<b>Sites Affected:</b>		<input checked="" type="checkbox"/> External Foundry/Subcon site(s)
<input type="checkbox"/> All site(s)	<input type="checkbox"/> not applicable	TOWER SEMICONDUCTOR
<input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Leshan, China		LTD

**Description and Purpose:**

FPCN21043X was published on 10 September 2015 announcing the transfer of the VHC1G, VHC1GT and SZ product family devices in the SC88A package to the TS18 wafer process at Tower Semiconductor and a change to the BOM for these same products to include Pd coated wire and Henkel mold compound.

This Update Notification is being published to inform that the Final Process Change Notification FPCN21043X is canceled. Manufacturing will continue to supply the TS60 wafer technology with existing BOM.

There are no changes to electrical performance or reliability of the devices listed.

**List of affected Standard Parts:**

M74VHC1G125DFT1G	M74VHC1GT126DF2G	MC74VHC1G02DFT2G	MC74VHC1G50DFT1G
M74VHC1G125DFT2G	M74VHC1GT14DFT1G	MC74VHC1G04DFT1G	MC74VHC1G50DFT2G
M74VHC1G126DFT1G	M74VHC1GT14DFT2G	MC74VHC1G04DFT2G	MC74VHC1G86DFT1G
M74VHC1G126DFT2G	M74VHC1GT32DFT1G	MC74VHC1G05DFT1G	MC74VHC1G86DFT2G
M74VHC1GT00DFT1G	M74VHC1GT32DFT2G	MC74VHC1G05DFT2G	MC74VHC1GU04DF1G
M74VHC1GT00DFT2G	M74VHC1GT50DFT1G	MC74VHC1G07DFT1G	NL17SZ07DFT2G
M74VHC1GT02DFT1G	M74VHC1GT50DFT2G	MC74VHC1G07DFT2G	NL17SZ125DFT2G
M74VHC1GT02DFT2G	M74VHC1GT86DFT1G	MC74VHC1G08DFT1G	NL17SZ08DFT2G
M74VHC1GT04DFT1G	M74VHC1GT86DFT2G	MC74VHC1G08DFT2G	NL17SZ32DFT2G
M74VHC1GT04DFT2G	M74VHC1GU04DFT1G	MC74VHC1G09DFT1G	NL17SZ00DFT2G
M74VHC1GT04DFT3G	M74VHC1GU04DFT2G	MC74VHC1G09DFT2G	NL17SZ04DFT2G
M74VHC1GT08DFT1G	MC74VHC1G00DFT1G	MC74VHC1G125DFT1G	NL17SZ126DFT2G
M74VHC1GT08DFT2G	MC74VHC1G00DFT2G	MC74VHC1G14DFT1G	NL17SZ06DFT2G
M74VHC1GT125DF1G	MC74VHC1G01DFT1G	MC74VHC1G14DFT2G	NL17SZ02DFT2G
M74VHC1GT125DF2G	MC74VHC1G01DFT2G	MC74VHC1G32DFT1G	NL17SZ86DFT2G
M74VHC1GT126DF1G	MC74VHC1G02DFT1G	MC74VHC1G32DFT2G	NL17SZ16DFT2G